



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN#20150127001
Marking Standardization for Select Devices assembled at Unisem
Information Only**

Date: 1/29/2015
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only. Please see the attachment details for the planned implementation date.

This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20150127001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CSD16301Q2	null
CSD17313Q2	null
CSD17313Q2Q1	null
CSD25302Q2	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20150127001	PCN Date:	01/29/2015
Title:	Marking Standardization for Select Devices Assembled at Unisem		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Datasheet
<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Part number change
<input type="checkbox"/>		<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

For the selected devices listed below, TI will change the marking format (additions **highlighted**) to align to TI standards as follows:

	Device Symbolization/Top Mark
From	<pre> +-----+ ! {CUST1} ! {CUST1} = DEVICE CODE ! YWWC ! Y = YEAR DATE CODE ! ! WW = WORK WEEK DATE CODE ! O ! C = COUNTRY CODE +-----+ O - PIN 1 (MARKED) LINE 1 MAXIMUM IS 4 CHARACTERS </pre>
TO	<pre> +-----+ ! {CUST1} ! {CUST1} = DEVICE CODE ! YMP ! YM = YEAR MONTH DATE CODE ! SLLL ! P = PRIMARY SITE CODE ! O ! S = SECONDARY SITE CODE +-----+ LLL = ASSY LOT CODE O - PIN 1 (MARKED) LINE 1 MAXIMUM IS 4 CHARACTERS </pre>

Reason for Change:

TI standardization

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Device symbolization.

Product Affected:

CSD13202Q2	CSD17313Q2	CSD25302Q2	CSD25310Q2T
CSD15571Q2	CSD17313Q2Q1	CSD25310Q2	XCSD85301Q2
CSD16301Q2	CSD17571Q2		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com